General Description

FSMOS® MOSFET is based on Oriental Semiconductor's unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. The high V_{th} series is specially designed to use in motor control systems with driving voltage of more than 10V.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery

RoHS compliant

Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switching mode power supply

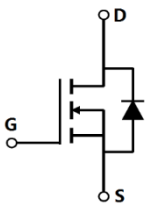
Key Performance Parameters

Parameter	Value	Unit
V_{DS}	100	V
$I_{D, pulse}$	800	A
$R_{DS(ON), max}$ @ V_{GS}=10V	2	mΩ
Q_g	134	nC

Marking Information

Product Name	Package	Marking
SFS10R02HNF	TO247	SFS10R02HN

Package & Pin information



Absolute Maximum Ratings at T_j=25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	100	V
Gate-source voltage	V_{GS}	±20	V
Continuous drain current[1], T_C=25 °C	I_D	360	A
Pulsed drain current[2], T_C=25 °C	$I_{D,\ pulse}$	800	A
Continuous diode forward current[1], T_C=25 °C	I_S	360	A
Diode pulsed current[2], T_C=25 °C	$I_{S,\ pulse}$	800	A
Power dissipation[3], T_C=25 °C	P_D	600	W
Single pulsed avalanche energy[4]	E_{AS}	540	mJ
Operation and storage temperature	T_{stg}, T_j	-55 to 175	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.25	°C/W
Thermal resistance, junction-ambient	$R_{\theta JA}$	62	°C/W

Electrical Characteristics at T_j=25°C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	100			V	V_{GS}=0 V, I_D=250 μA
Gate threshold voltage	$V_{GS(th)}$	2		4	V	V_{DS}=V_{GS}, I_D=250 μA
Drain-source on-state resistance	$R_{DS(ON)}$		1.5	2	mΩ	V_{GS}=10 V, I_D=50 A
Gate-source leakage current	I_{GSS}			100	nA	V_{GS}=20 V
				-100		V_{GS}=-20 V
Drain-source leakage current	I_{DSS}			1	μA	V_{DS}=100 V, V_{GS}=0 V
Gate resistance	R_G		1		Ω	f=1 MHz, Open drain

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}		9750		pF	V_{GS}=0 V, V_{DS}=25 V, f=100 kHz
Output capacitance	C_{oss}		5450		pF	
Reverse transfer capacitance	C_{rss}		312		pF	
Turn-on delay time	$t_{d(on)}$		28		ns	V_{GS}=10 V, V_{DS}=50 V, R_G=2 Ω, I_D=25 A
Rise time	t_r		25		ns	
Turn-off delay time	$t_{d(off)}$		59		ns	
Fall time	t_f		24		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		134		nC	V_{GS}=10 V, V_{DS}=50 V, I_D=25 A
Gate-source charge	Q_{gs}		36		nC	
Gate-drain charge	Q_{gd}		28		nC	
Gate plateau voltage	$V_{plateau}$		4.4		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V_{SD}			1.3	V	I_S=30 A, V_{GS}=0 V
Reverse recovery time	t_{rr}		138		ns	V_R=50 V, I_S=25 A, di/dt=100 A/μs
Reverse recovery charge	Q_{rr}		247		nC	
Peak reverse recovery current	I_{rrm}		3.3		A	

Note

1) Calculated continuous current based on maximum allowable junction temperature.
2) Repetitive rating; pulse width limited by max. junction temperature.
3) Pd is based on max. junction temperature, using junction-case thermal resistance.
4) V_{DD}=50V,V_{GS}=10 V, L=0.3 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

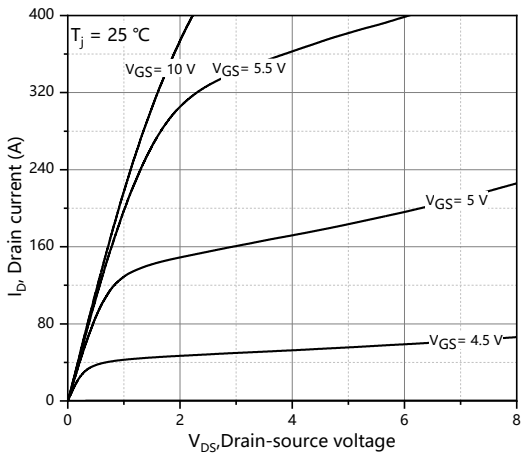


Figure 1. Typ. output characteristics

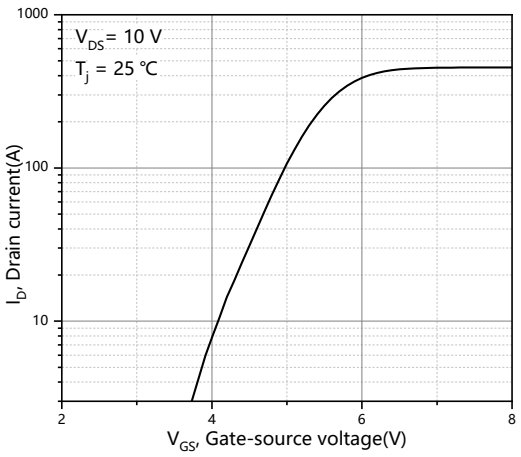


Figure 2. Typ. transfer characteristics

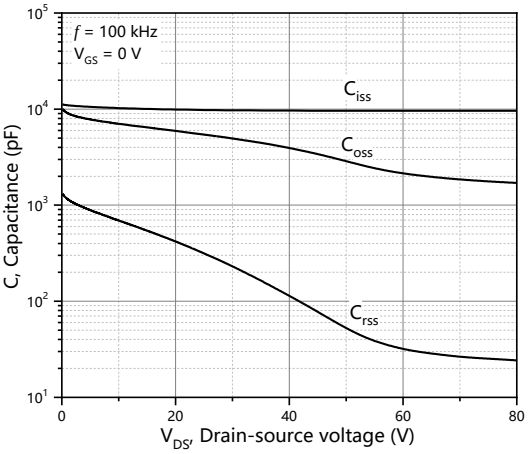


Figure 3. Typ. capacitances

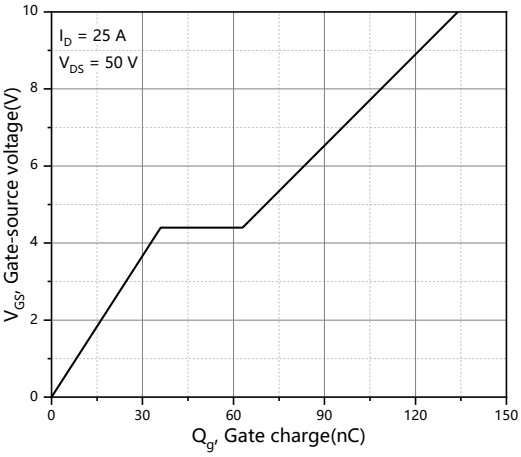


Figure 4. Typ. gate charge

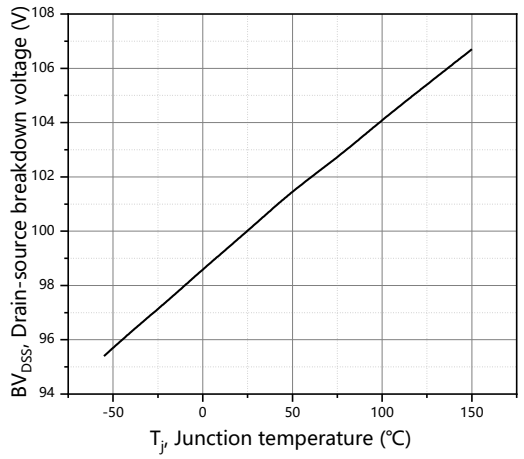


Figure 5. Drain-source breakdown voltage

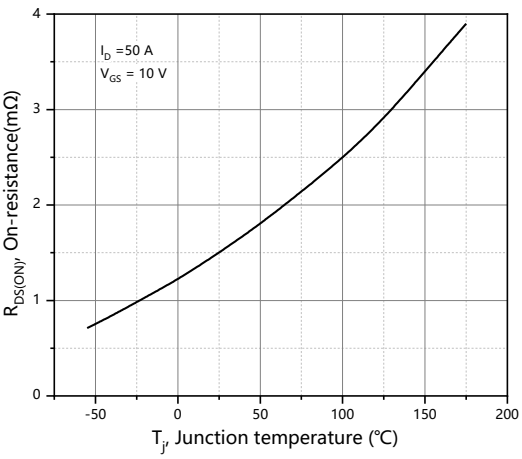


Figure 6. Drain-source on-state resistance

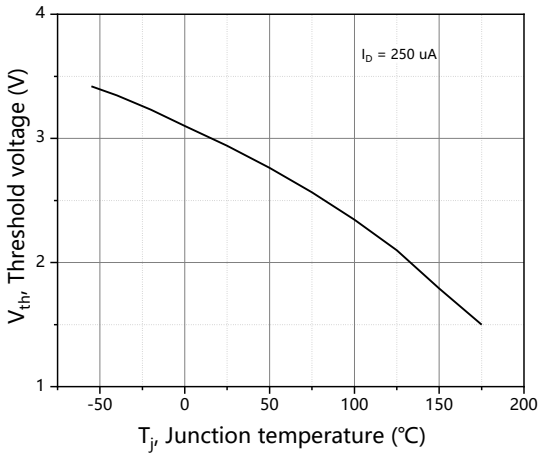


Figure 7. Threshold voltage

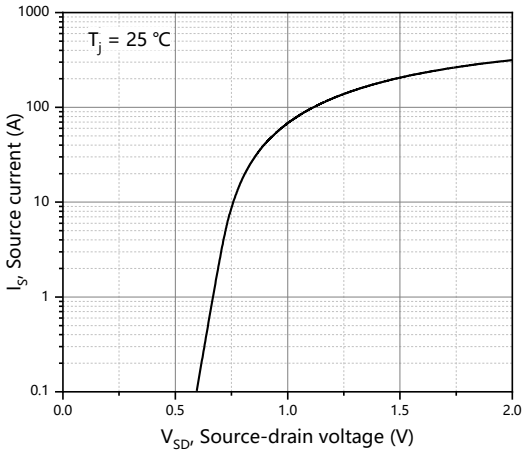


Figure 8. Forward characteristic of body diode

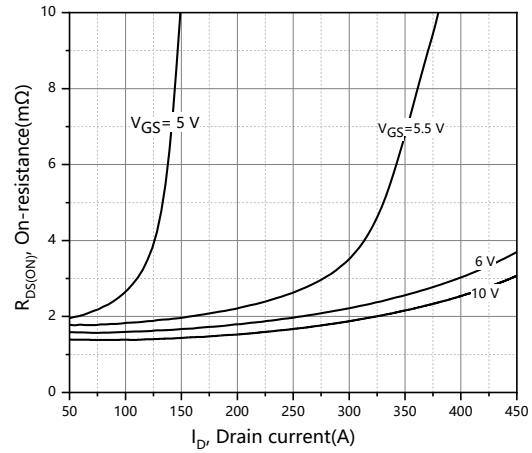


Figure 9. Drain-source on-state resistance

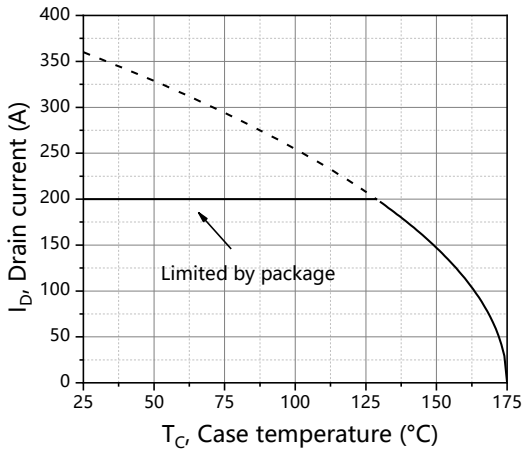


Figure 10. Drain current

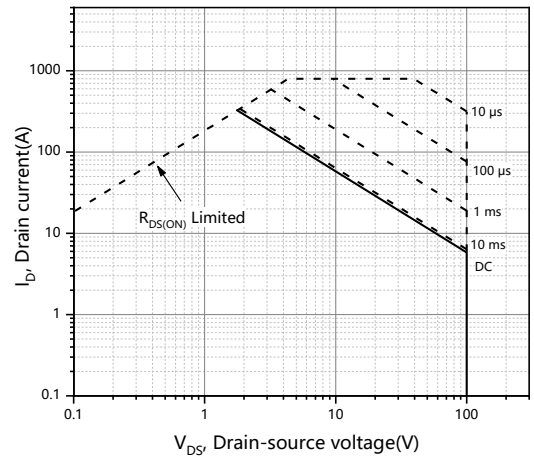


Figure 11. Safe operation area T_C=25℃

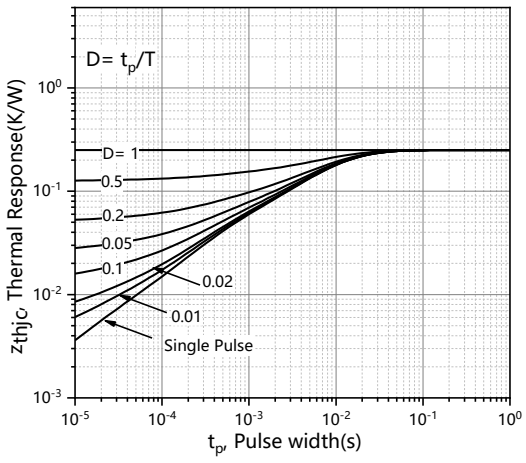


Figure 12. Max. transient thermal impedance

Test circuits and waveforms

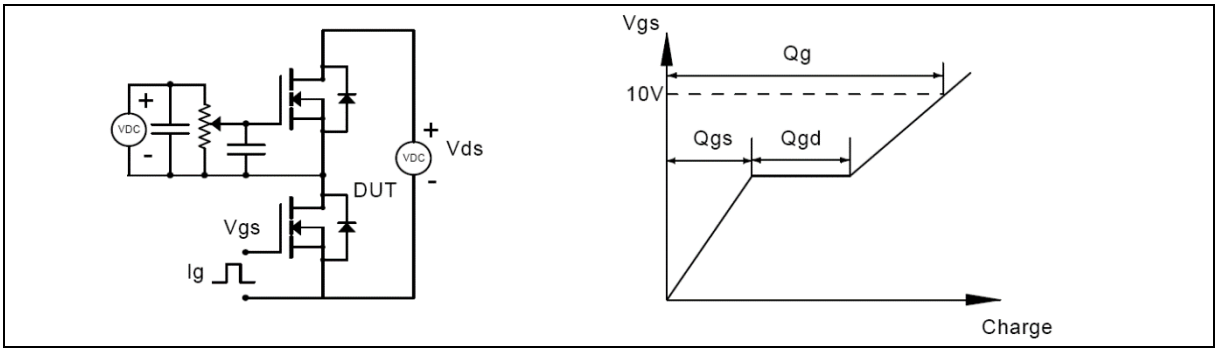


Figure 1. Gate charge test circuit & waveform

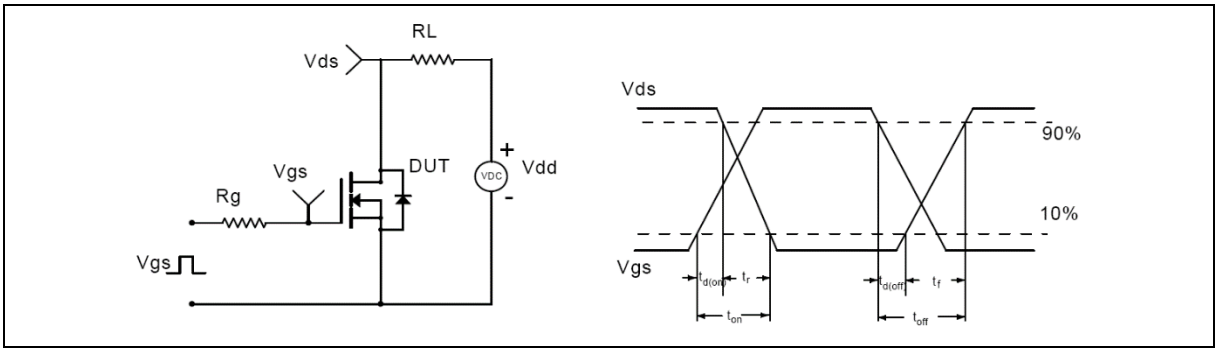


Figure 2. Switching time test circuit & waveforms

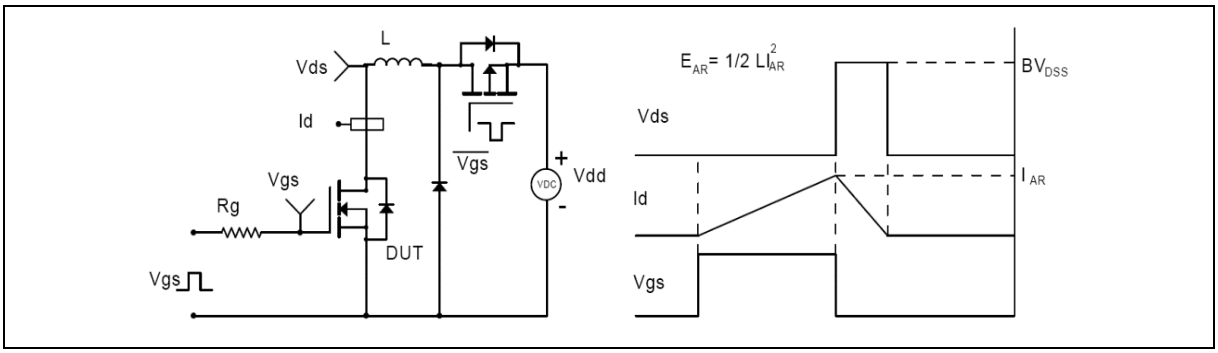


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

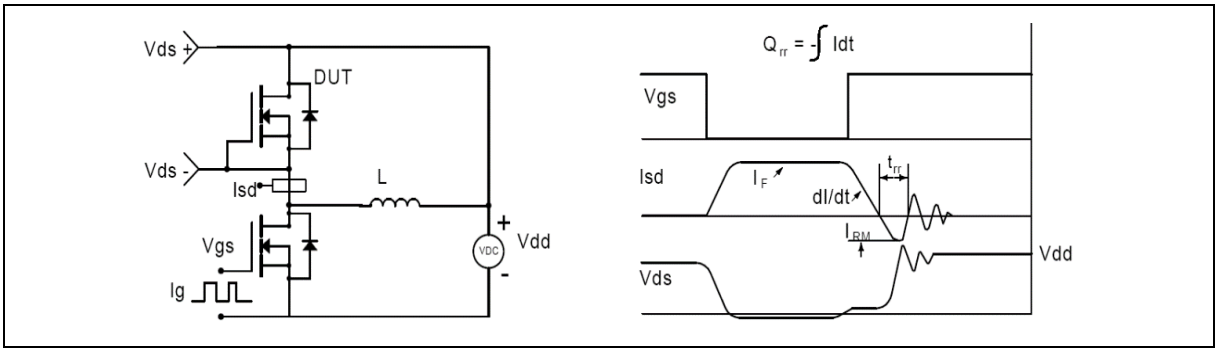
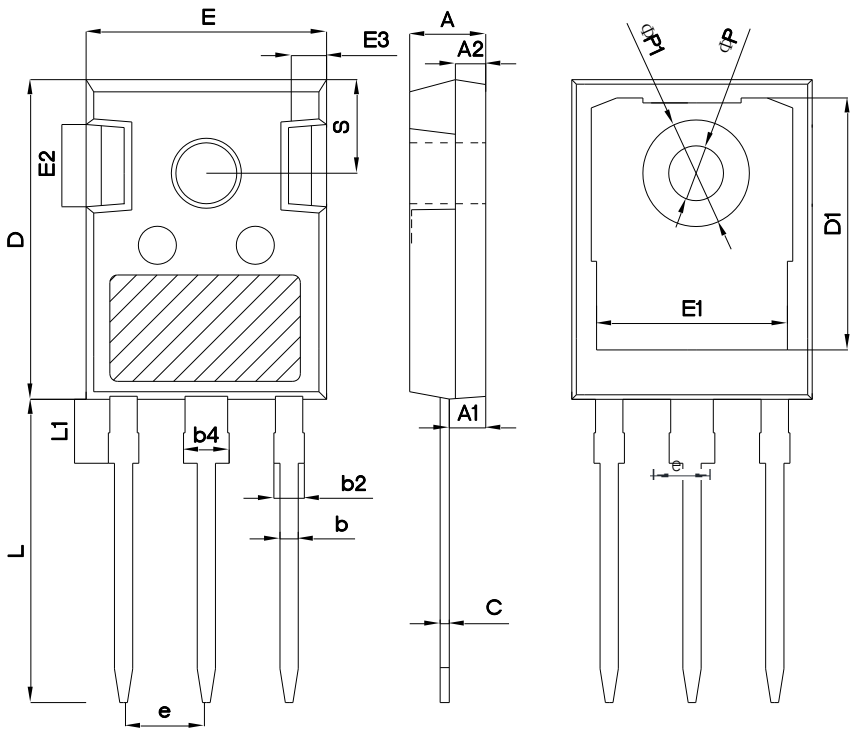


Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.80	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44 BSC		
L	19.82	19.92	20.22
L1	-	-	4.30
ΦP	3.40	3.60	3.80
ΦP1	-	-	7.30
S	6.15 BSC		

Version: TO247-P package outline dimension

Ordering Information

Package Type	Units/ Tube	Tubes / Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO247-P	30	11	330	6	1980

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFS10R02HNF	TO247	yes	yes	yes

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Revision History

Version	Revision History	Date
V1.0	Initial release	2023-07-19
V1.1	Update Rdson typ. Update figure 6 & figure 9 & figure 11	2025-07-15

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